



# MHS

## data sheet

T-46-23-12

# HM 65764

## 8K x 8

### HIGH SPEED CMOS SRAM

OCTOBER 1987

#### Features

- FAST ACCESS TIME : 35/45/55 ns max
- STANDBY CURRENT : 20 mA
- OPERATING CURRENT : 150 mA
- ASYNCHRONOUS INPUTS
- TTL COMPATIBLE INPUTS AND OUTPUTS
- SINGLE 5 VOLT SUPPLY
- 300 MILS WIDTH PACKAGE
- CAPABLE OF WITHSTANDING GREATER THAN 2000V ELECTROSTATIC DISCHARGE
- WIDE TEMPERATURE RANGE : - 55°C TO + 125°C

#### Description

The HM 65764 is a high speed CMOS static RAM organised as 8192 x 8 bits. It is manufactured using MHS's high performance, CMOS technology.

Access times as fast as 35 ns are available with maximum power consumption of only 825 mW.

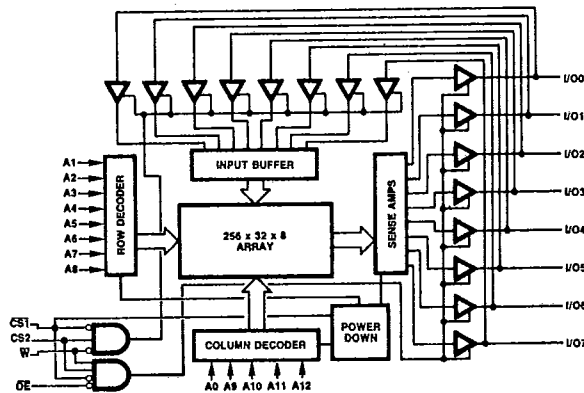
The HM 65764 features fully static operation requiring no external clocks or timing strobes, additionally the automatic power-down feature reduces the power consumption by 73 % when deselected. Easy memory expansion is provided by an active low chip select (CS1) and three state drivers, an active high chip select (CS2), an active low output enable.

All inputs and outputs of the HM 65764 are TTL compatible and operate from a single 5V supply thus simplifying system design.

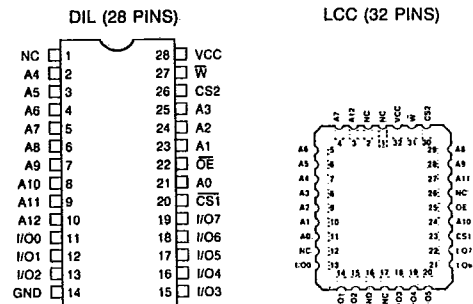
The HM 65764 is packaged in a plastic/ceramic 300 mils 28 pins DIL, SO 28 pins DIL, or a 32 pins Leadless Chip Carrier allowing high board-level packing densities.

The HM 65764 is 100 % processed following the test methods of MIL STD 883C.

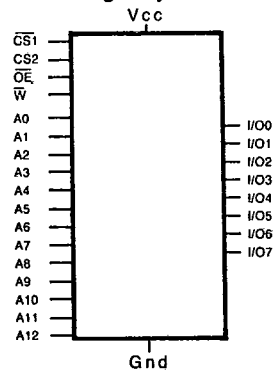
#### Block Diagram



#### Pinouts (TOP VIEW)



#### Logic Symbol



#### PIN NAMES

A0-A12 : Address inputs	OE : Output enable
I/O : Input/Output	Gnd : Ground
CS1-CS2 : Chip select	W : Write enable
Vcc : Power	

#### TRUTH TABLE

CS1	CS2	OE	W	Din	Dout	MODE
H	X	X	X	Z	Z	Deselect (power down)
L	H	L	H	Valid	Valid	Read
L	H	X	L	Valid	Z	Write
L	H	H	H	Z	Z	Deselect
X	L	X	X	Z	Z	Deselect

L = Low, H = High, X = H or L

<p><b>• ABSOLUTE MAXIMUM RATINGS</b></p> <p>Supply voltage to GND potential: -0.5 V* to + 7.0V                  DC input or output voltage: - 3.0V to 7.0V                  DC output voltage in high Z state: - 0.5V to 7.0V                  Storage temperature: - 65° C to + 150° C                  Output current into outputs (low): 20 mA</p>	<p><b>• OPERATING RANGE</b></p> <p>Military (- 2)                  Commercial (- 5)</p>	<p>Operating Voltage</p> <p>VCC ± 10 %                  VCC ± 10 %</p>	<p>Operating Temperature</p> <p>- 55° C to + 125° C                  0° C to + 70° C</p>
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Electro Static Discharge Voltage = 2000V  
 (per MIL STD 883, Method 3015.2)

**ELECTRICAL CHARACTERISTICS**

**DC PARAMETERS**

Symbol	Parameter	65764K-5 65764M-5	65764M-2	65764N-5	65764N-2	Unit	Value
ICCSB1 (1)	Stand by supply current	40	40	40	40	mA	max
ICCSB2 (2)	Stand by supply current	20	20	20	20	mA	max
ICCOP (3)	Average operating supply current	150	150	150	150	mA	max
IIX (4)	Input leakage current	± 10	± 10	± 10	± 10	µA	max
IOZ (4)	Output leakage current	± 10	± 10	± 10	± 10	µA	max
VIL (5)	Input low voltage	0.8	0.8	0.8	0.8	V	max
VIH (5)	Input high voltage	2.2	2.2	2.2	2.2	V	min
VOL (6)	Output low voltage	0.4	0.4	0.4	0.4	V	max
VOH (6)	Output high voltage	2.4	2.4	2.4	2.4	V	min
I OS (7)	Output short circuit current	- 350	- 350	- 350	- 3	mA	max
C IN (8)	Input capacitance	5	5	5	5	pF	max
C OUT (8)	Output capacitance	7	7	7	7	pF	max

- Note 1 :  $\overline{CS} \geq V_{IH}$
- Note 2 :  $\overline{CS} \geq V_{CC} - 0.3V$ ,  $V_{IN} \geq V_{CC} - 0.3V$  or  $V_{IN} \leq 0.3V$
- Note 3 : VCC max, Iout = 0 mA
- Note 4 :  $GND \leq V_I \leq V_{CC}$ ,  $GND \leq V_O \leq V_{CC}$  Output disabled
- Note 5 : VIL min = - 3.0V, VIH max = VCC
- Note 6 : VCC = min, IOH = - 4 mA, IOL = 8.0 mA
- Note 7 : VCC = max, Vout = GND, duration of the short circuit should not exceed 30 seconds.  
 Not more than 1 output should be shorted at one time
- Note 8 : This parameter is sampled and not 100 % tested. TA = 25°C, F = 1 MHz, VCC = 5.0V



**AC PARAMETERS :**

Conditions : Input pulse levels                    GND to 3.0V  
 Input rise    5 ns  
 Input timing reference levels                    1.5V  
 Output loading IOL/IOH (see fig. 1a and 1b) + 30 pF

**Read cycle**

Parameter	Description	65764-K5	65764M-5	65764M-2	65764N-5	65764N-2	Unit	Value
TAVAV	Read cycle time	35	45	45	55	55	ns	min
TAVQV	Address to data valid	35	45	45	55	55	ns	max
TAVQX	Data hold from address change	3	5	5	5	5	ns	min
TEL1QV	$\overline{CS1}$ low to data valid	35	45	45	55	55	ns	max
TEL2QV	CS2 high to data valid	35	45	45	55	55	ns	max
TEL1QX	$\overline{CS1}$ low to low Z (9)	5	10	10	10	10	ns	min
TEH2QX	CS2 low to low Z	5	10	10	10	10	ns	max
TEH1QZ	$\overline{CS1}$ high to high Z (8, 9)	15	20	20	20	20	ns	max
TEL2QZ	CS2 low to high Z	15	20	20	20	20	ns	max
TELIC	$\overline{CS1}$ low to power up	0	0	0	0	0	ns	min
TEHICCL	$\overline{CS1}$ high to power down	20	25	25	25	25	ns	max
TGLQV	$\overline{OE}$ low to data valid	15	20	20	25	25	ns	max
TGLQX	$\overline{OE}$ low to low Z	0	0	0	0	0	ns	min
TGHQZ	$\overline{OE}$ high to high Z	20	25	25	30	30	ns	max

**Write cycle (10)**

Parameter	Description	65764K-5	65764M-5	65764M-2	65764N-5	65764N-2	Unit	Value
TAVAV	Write cycle time	30	40	40	50	50	ns	min
TEL1WH	$\overline{CS1}$ low to write end	30	40	40	45	45	ns	min
TEH2WH	CS2 high to write end	30	40	40	45	45	ns	min
TAVWH	Address set up to write end	30	40	40	45	45	ns	min
TWHAX	Address hold from write end	0	0	0	0	0	ns	min
TAVWL	Address set up to write start	0	0	0	0	0	ns	min
TWLWH	$\overline{W}$ pulse width	20	25	25	30	30	ns	min
TDVWH	Data set up to write end	15	20	20	25	25	ns	min
TWHDX	Data hold from write end	0	0	0	0	0	ns	min
TWLQZ	$\overline{W}$ high to low Z (10)	15	20	20	20	20	ns	max
TWHQX	$\overline{W}$ low to high Z (9, 10)	0	0	0	0	0	ns	min

**Note 9 :** TEHQZ, TWLQZ are tested with  $C1 = 5$  pF as in figure 1b. Transition is measured  $\pm 500$  mV from steady state voltage.

**Note 10 :** At any given temperature and voltage condition, TEHQZ is less than TELQX for all devices. These parameters are sampled and not 100 % sampled.

**Note 11 :** The data input set up and hold timing should be referenced to the rising edge of the signal that terminates the write.



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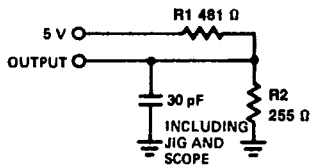


Figure 1a

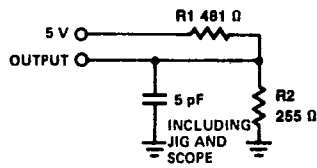


Figure 1b

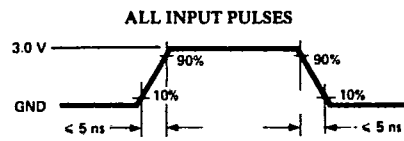
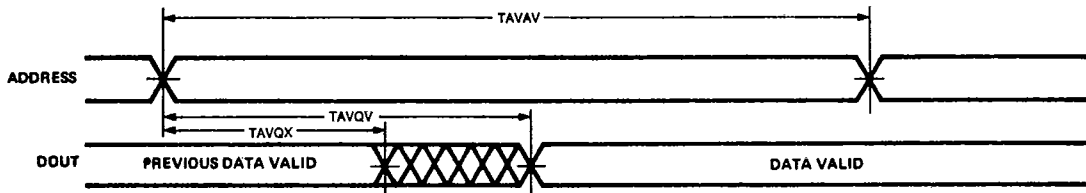


Figure 2

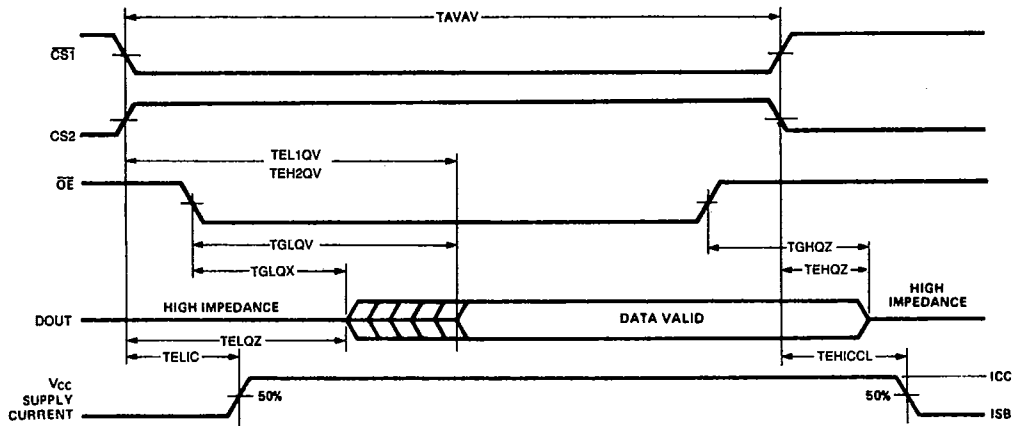
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Switching Waveforms

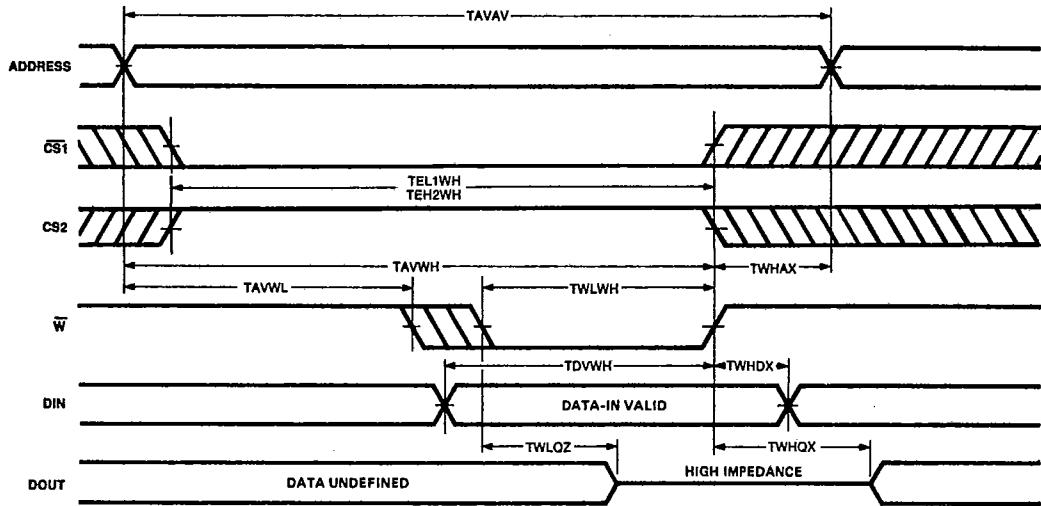
READ CYCLE No. 1 (Notes 11, 12)



READ CYCLE No. 2 (Notes 11, 13)

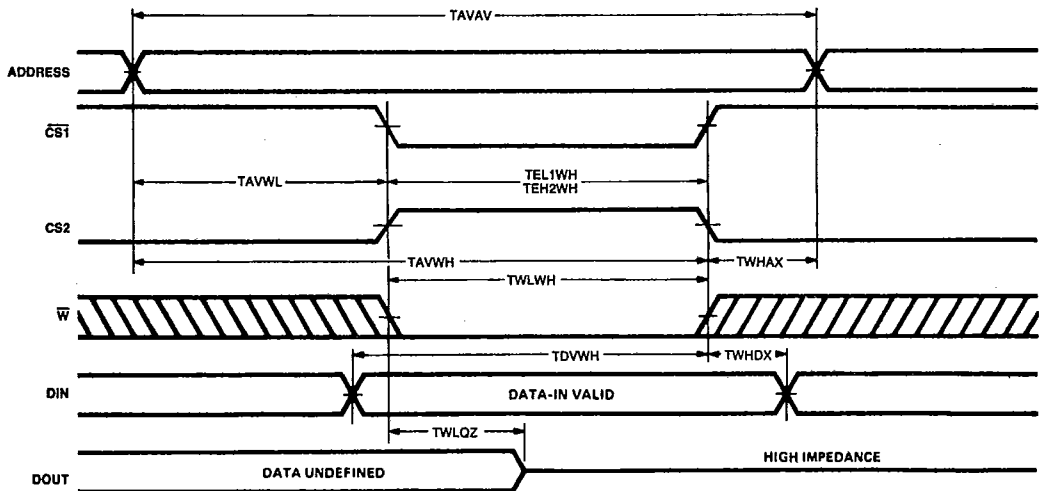


Write Cycle No. 1 ( $\bar{W}$  Controlled) (Note 7)



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Write Cycle No. 2 ( $\bar{CS}$  Controlled) (Note 7)



Note : If  $\bar{CS}$  goes high simultaneously with  $\bar{W}$  high, the output remains in a high impedance state.

Note 12 :  $\bar{W}$  is high for read cycle.

Note 13 : Device is continuously selected,  $\bar{CS} = V_{IL}$ .

Note 14 : Address valid prior to or coincident with  $\bar{CS}$  transition low.



HM 65764

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Ordering information

DEVICE TYPE	PACKAGE	TEMPERATURE RANGE
HM1-65764 ( ) -5	CERAMIC DIL	0°C to + 70°C
HM1-65764 ( ) -2	CERAMIC DIL	- 55°C to + 125°C
HM1-65764 ( ) -8	CERAMIC DIL	- 55°C to + 125°C
HM3-65764 ( ) -5	PLASTIC DIL	0°C to + 70°C
HMT-65764 ( ) -5	SO PLASTIC DIL	0°C to + 70°C
HM4-65764 ( ) -5	LCC 28 pin	0°C to + 70°C
HM4-65764 ( ) -2	LCC 28 pin	- 55°C to + 125°C
HM4-65764 ( ) -8	LCC 28 pin	- 55°C to + 125°C

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TEMPERATURE RANGE (- 2, - 5, - 8)

PERFORMANCE :

- K : 35 ns (commercial only)
- M : 45 ns
- N : 55 ns

DEVICE TITLE

PACKAGE (1, 3, 4, T)

- 1 : CERAMIC
- 3 : PLASTIC
- 4 : LCC
- T : SO

